

Mentor Program

What is the E-Buddy Mentoring Program?

A program provided by members of SHPE-Santa Barbara to establish a strong relationship through e-mail, activities, workshops and socials. The main communication will be through e-mail where the student can easily address any questions s/he may have regarding her/his major, course work, or job hunting advice.

Who can join?

Any engineering student at UCSB or SBCC. Priority is given to Los Ingenieros members and SBCC engineering students but all students are welcome to apply.

For more information on SHPE –SB and its E-Buddy Program, please contact:

Armando Veloz, External VP
armandoveloz@msn.com

MESA Engineering Program at UCSB

The MESA Engineering Program (MEP) is a student support program designed to assist in the academic and professional development of under-represented students pursuing undergraduate degrees in UC Santa Barbara's College of Engineering. MEP offers a comprehensive program that maximizes student's academic potential, while preparing them for their career as a professional engineer.

For more information of UC Santa Barbara's MESA Program, please contact:

Phyllis Brady, Director (805) 893-4026
pbrady@engineering.ucsb.edu

MESA Community College Program at Santa Barbara City College

The MESA Community College Program (MCCP) is also a support program designed to assist community college students interested in transferring to a university in math, engineering and science. The MESA program supports the students with a variety of services, two of them being student leadership and professional development.

For more information of Santa Barbara City College MESA Program, please contact:
Virginia Estrella, Director (805) 730-4792
estrella@sbcc.edu

E-Buddy Program Application

Please fill in the following:

Name:

Local Address:

Local Phone: _____

Major: _____

E-mail: _____

Hobbies: _____

Music: _____

Hometown: _____

Please submit your application to:

SHPE-Santa Barbara
P.O. Box 8745
Goleta, Ca. 93118
Attention: E-Buddies Program

Deadline: Postmark by Nov 9, 2009

